

BigTwin SuperServer SYS-221BT-HNTR



More details here

Key Applications

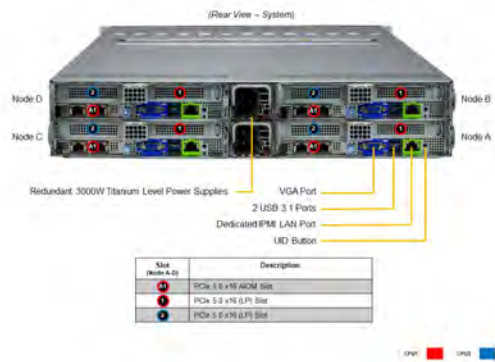
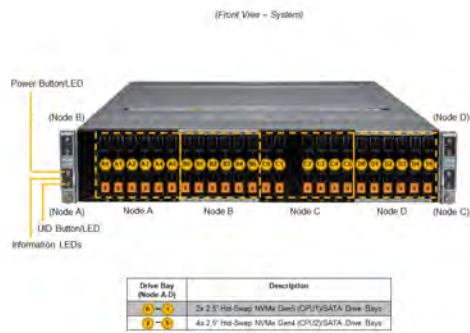
All-Flash NVMe Hyperconverged Infrastructure, Container-as-a-Service;
Application Accelerator, High-Performance File System, Diskless HPC Clusters,

Key Features

- Socket E (LGA 4677) support 4th Gen Intel® Xeon® Scalable processors;
- Intel® C741;
- Up to 16 DIMMs ECC DDR5 Slots;
- 2 PCIe 5.0 x16 (LP) slot; Tool-less support; Optional M.2 NVMe Boot Controller via SCC-A2NM2241G3-B1; Internal PCIe 4.0 x8 for 2 M.2 NVMe support onboard;
- Network connectivity via AIOM (OCP 3.0 compliant);
- 6 hot-swap 2.5" drive bays (2x PCIe 5.0 NVMe and 4x PCIe 4.0 NVMe/SATA);
- 4 cooling fans per 2U enclosure, 16K RPM; Shared Cooling Design, Counter-Rotating; Liquid Cooling Support;
- 3000W Redundant Power Supplies Titanium Level (96%+); Shared Power Design;



Form Factor	2U Rackmount Enclosure: 449 x 88 x 730mm (17.68" x 3.47" x 28.75") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	4th Gen Intel® Xeon® Scalable processors Dual Socket LGA 4677 (Socket E) supported Intel Xeon CPU Max Series with high bandwidth memory (HBM) (Supports up to 350W TDP CPUs (Liquid Cooled), Supports up to 205W TDP CPUs (Aircooled)*, *CPUs (air cooled) with TDP over 205W are only supported under specific conditions. Contact customer support for details.)
Drive Bays	6x 2.5" hot-swap NVMe/SATA drive bays; Optional RAID support via Intel® PCH
Expansion Slots	2 PCIe 5.0 x16 LP slot(s)
On-Board Devices	Chipset: Intel® C741 Network Connectivity: Via AIOM IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 RJ45 Dedicated BMC LAN port USB: 2 USB 3.1 port(s) (2 rear) Video: 1 VGA port(s) Others: 2x M.2 for boot drive or caching M.2 form factor: NVMe double-sided 22x110mm Note: Enterprise-grade M.2 only for caching application



System Cooling	4x 16K RPM Counter Rotating 8cm Fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	3000W 1U Redundant Power Supply Dimension (W x H x L): 45 x 40 x 480 mm
System BIOS	BIOS Type: AMI 32MB Flash ROM
Management	SuperDoctor® 5; Watch Dog; SUM; IPMI 2.0; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; SuperCloud Composer; Supemicro Out of Band (OOB) License (Included per Node)
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator
Dimensions and Weight	Height: 3.47" (88 mm) Width: 17.68" (449 mm) Depth: 28.75" (730 mm) Gross Weight: 96.6 lbs (43.8 kg) Net Weight: 66.1 lbs (30 kg) Packaging: 9.76" (H) x 24.65" (W) x 45.28" (D) Available Color: Black front & silver body
Operating Environment	ROHS: RoHS Compliant Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (Non-Condensing) Non-operating Relative Humidity: 5% to 95% (Non-Condensing)
Motherboard	Super X13DET-B
Chassis	CSE-217BQ2-R3K04P